



## Description

The DMPH6250SQ-13 uses advanced trench technology to provide excellent  $R_{DS(ON)}$ . This device is suitable for use as a load switch or in PWM applications.

## General Features

$V_{DS} = -60V, I_D = -3A$

$R_{DS(ON)} < 140m\Omega @ V_{GS} = -10V$

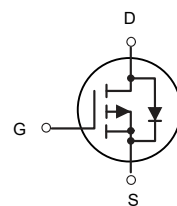
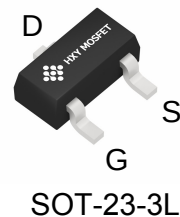
$R_{DS(ON)} < 190m\Omega @ V_{GS} = -4.5V$

## Application

Battery protection

Load switch

Uninterruptible power supply



P-Channel MOSFET

## Package Marking and Ordering Information

| Product ID    | Pack      | Brand      | Qty(PCS) |
|---------------|-----------|------------|----------|
| DMPH6250SQ-13 | SOT-23-3L | HXY MOSFET | 3000     |

## Absolute Maximum Ratings ( $T_A = 25^\circ C$ unless otherwise noted)

| Symbol          | Parameter                                        | Limit      | Unit         |
|-----------------|--------------------------------------------------|------------|--------------|
| $V_{DS}$        | Drain-Source Voltage                             | -60        | V            |
| $V_{GS}$        | Gate-Source Voltage                              | $\pm 20$   | V            |
| $I_D$           | Drain Current-Continuous                         | -3         | A            |
| $I_{DM}$        | Drain Current-Pulsed (Note 1)                    | -6         | A            |
| $P_D$           | Maximum Power Dissipation                        | 1.5        | W            |
| $T_J, T_{STG}$  | Operating Junction and Storage Temperature Range | -55 To 150 | $^\circ C$   |
| $R_{\theta JA}$ | Thermal Resistance, Junction-to-Ambient (Note 2) | 85         | $^\circ C/W$ |



**Electrical Characteristics (T<sub>J</sub>=25°C, unless otherwise noted)**

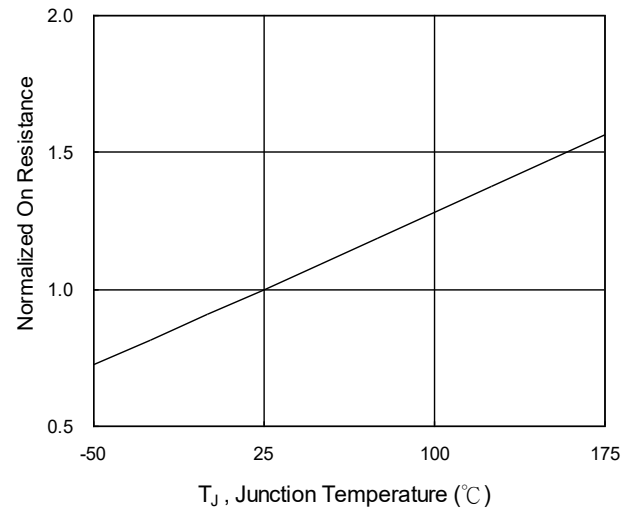
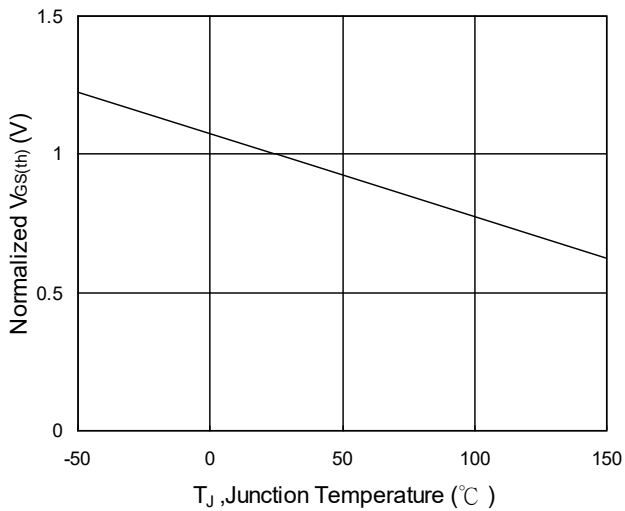
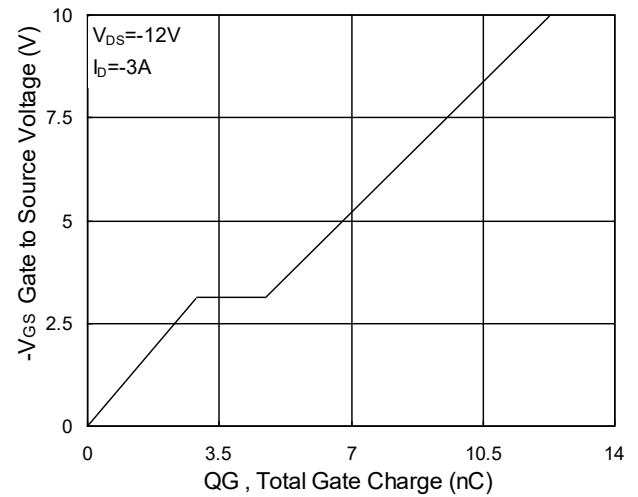
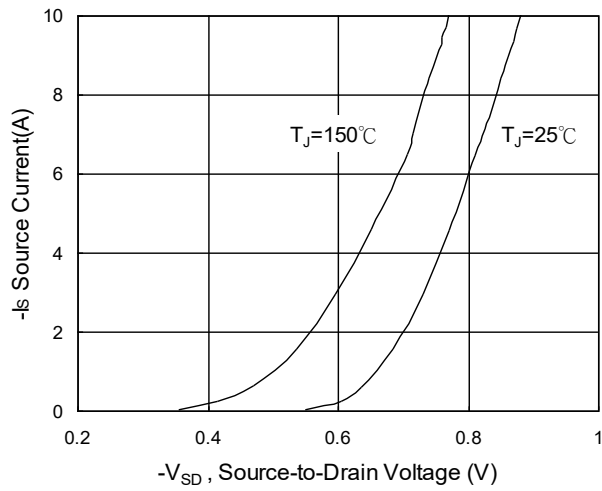
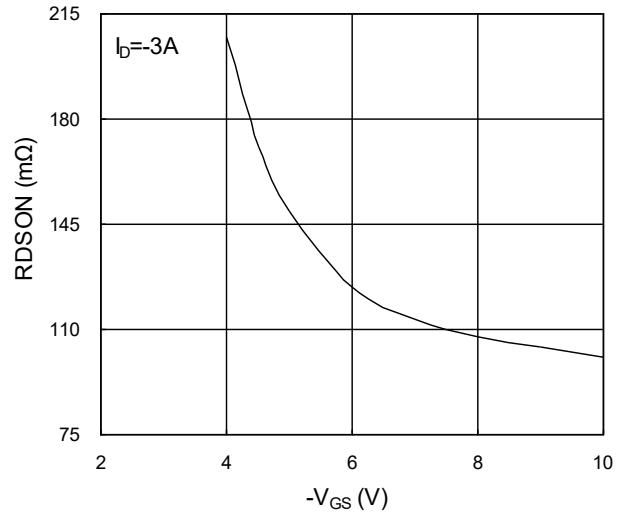
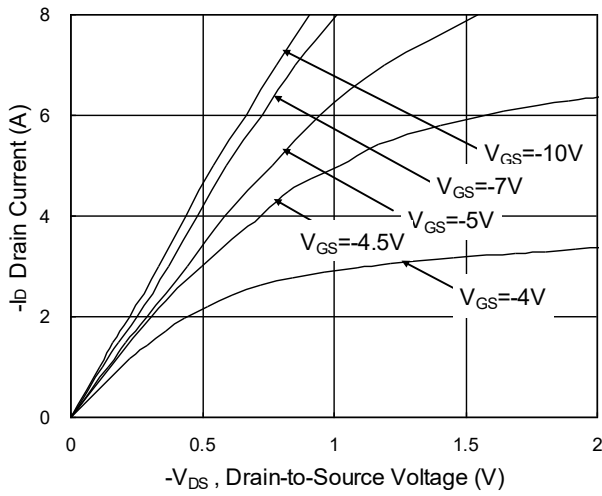
| Symbol                              | Parameter                                      | Conditions                                                                                 | Min. | Typ.   | Max. | Unit  |
|-------------------------------------|------------------------------------------------|--------------------------------------------------------------------------------------------|------|--------|------|-------|
| BV <sub>DSS</sub>                   | Drain-Source Breakdown Voltage                 | V <sub>GS</sub> =0V, I <sub>D</sub> =-250μA                                                | -60  | ---    | ---  | V     |
| ΔBV <sub>DSS</sub> /ΔT <sub>J</sub> | BV <sub>DSS</sub> Temperature Coefficient      | Reference to 25°C, I <sub>D</sub> =-1mA                                                    | ---  | -0.049 | ---  | V/°C  |
| R <sub>DS(ON)</sub>                 | Static Drain-Source On-Resistance <sup>2</sup> | V <sub>GS</sub> =-10V, I <sub>D</sub> =-3A                                                 | ---  | 115    | 140  | mΩ    |
|                                     |                                                | V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-2A                                                | ---  | ---    | 190  |       |
| V <sub>GS(th)</sub>                 | Gate Threshold Voltage                         | V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =-250μA                                  | -1.0 | ---    | -2.5 | V     |
| ΔV <sub>GS(th)</sub>                | V <sub>GS(th)</sub> Temperature Coefficient    |                                                                                            | ---  | 5.42   | ---  | mV/°C |
| I <sub>DSS</sub>                    | Drain-Source Leakage Current                   | V <sub>DS</sub> =-48V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C                           | ---  | ---    | 1    | μA    |
|                                     |                                                | V <sub>DS</sub> =-48V, V <sub>GS</sub> =0V, T <sub>J</sub> =150°C                          | ---  | ---    | 5    |       |
| I <sub>GSS</sub>                    | Gate-Source Leakage Current                    | V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V                                                 | ---  | ---    | ±100 | nA    |
| g <sub>fs</sub>                     | Forward Transconductance                       | V <sub>DS</sub> =-5V, I <sub>D</sub> =-3A                                                  | ---  | 5.8    | ---  | S     |
| Q <sub>g</sub>                      | Total Gate Charge (-4.5V)                      | V <sub>DS</sub> =-20V, V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-3A                         | ---  | 5.9    | ---  | nC    |
| Q <sub>gs</sub>                     | Gate-Source Charge                             |                                                                                            | ---  | 2.9    | ---  |       |
| Q <sub>gd</sub>                     | Gate-Drain Charge                              |                                                                                            | ---  | 1.8    | ---  |       |
| T <sub>d(on)</sub>                  | Turn-On Delay Time                             | V <sub>DD</sub> =-12V, V <sub>GS</sub> =-10V, R <sub>G</sub> =3.3Ω,<br>I <sub>D</sub> =-3A | ---  | 10     | ---  | ns    |
| T <sub>r</sub>                      | Rise Time                                      |                                                                                            | ---  | 17     | ---  |       |
| T <sub>d(off)</sub>                 | Turn-Off Delay Time                            |                                                                                            | ---  | 22     | ---  |       |
| T <sub>f</sub>                      | Fall Time                                      |                                                                                            | ---  | 21     | ---  |       |
| C <sub>iss</sub>                    | Input Capacitance                              | V <sub>DS</sub> =-15V, V <sub>GS</sub> =0V, F=1MHz                                         | ---  | 715    | ---  | pF    |
| C <sub>oss</sub>                    | Output Capacitance                             |                                                                                            | ---  | 51     | ---  |       |
| C <sub>rss</sub>                    | Reverse Transfer Capacitance                   |                                                                                            | ---  | 34     | ---  |       |
| I <sub>S</sub>                      | Continuous Source Current <sup>1,6</sup>       | V <sub>G</sub> =V <sub>D</sub> =0V, Force Current                                          | ---  | ---    | -3   | A     |
| I <sub>SM</sub>                     | Pulsed Source Current <sup>2,6</sup>           |                                                                                            | ---  | ---    | -6   | A     |
| V <sub>SD</sub>                     | Diode Forward Voltage <sup>2</sup>             | V <sub>GS</sub> =0V, I <sub>S</sub> =-1A, T <sub>J</sub> =25°C                             | ---  | ---    | -1.2 | V     |

Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3.The EAS data shows Max. rating . The test condition is V<sub>DD</sub>=-25V,V<sub>GS</sub>=-10V,L=0.1mH,I<sub>AS</sub>=-20A
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I<sub>D</sub> and I<sub>DM</sub> , in real applications , should be limited by total power dissipation.



### P-Channel Typical Characteristics



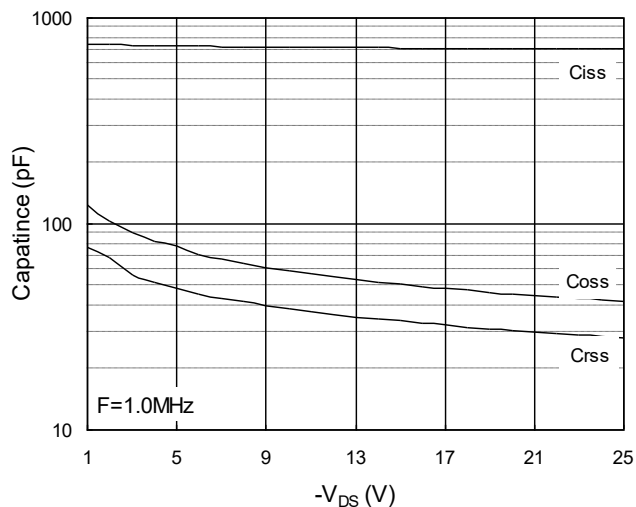


Fig.7 Capacitance

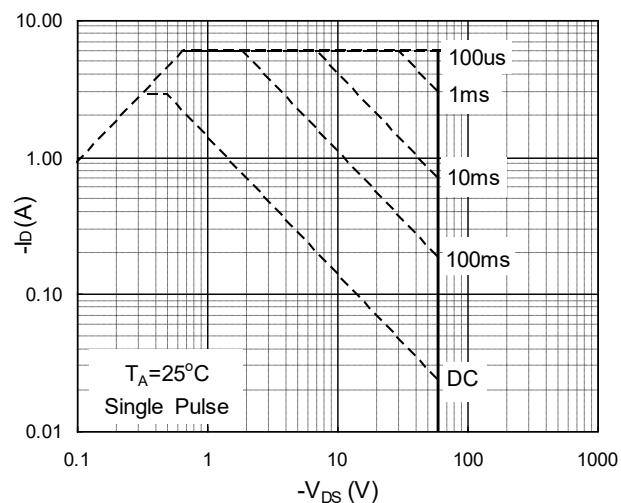


Fig.8 Safe Operating Area

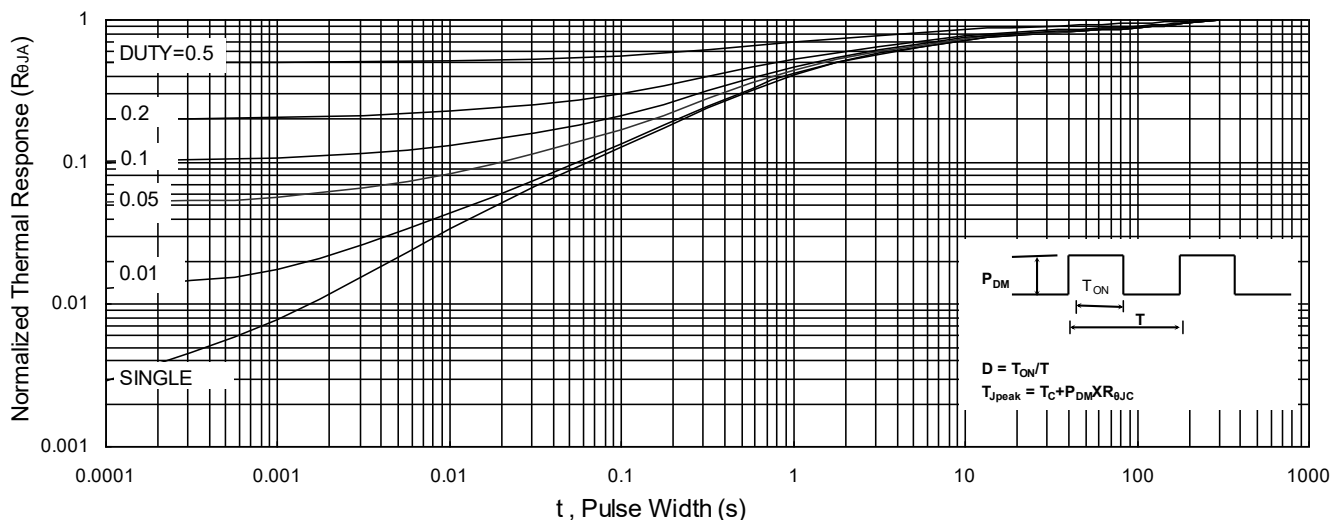


Fig.9 Normalized Maximum Transient Thermal Impedance

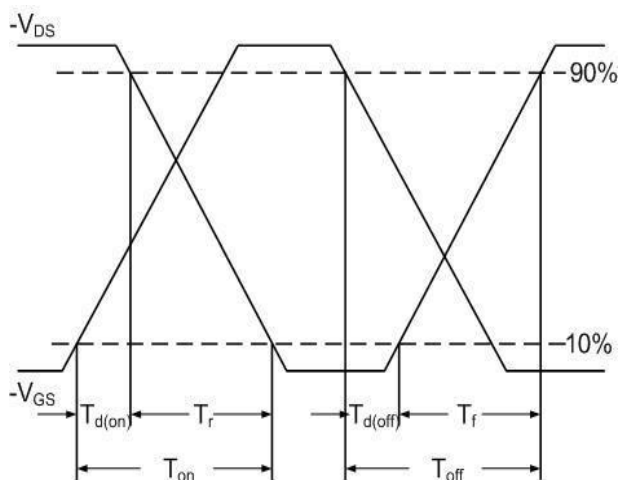


Fig.10 Switching Time Waveform

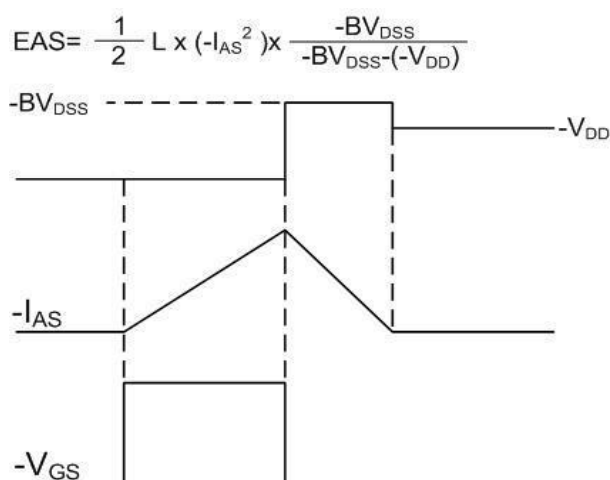
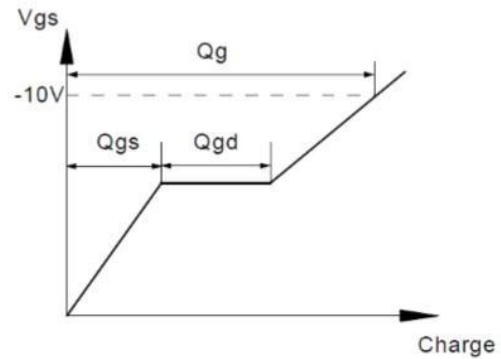
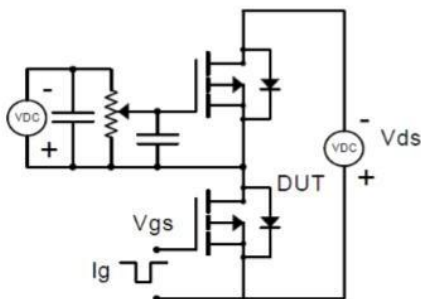


Fig.11 Unclamped Inductive Waveform

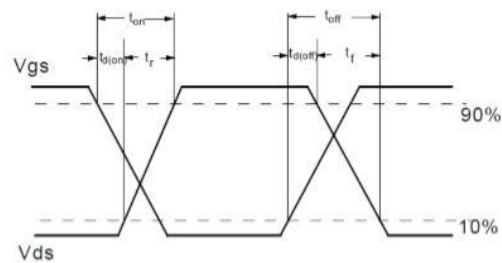
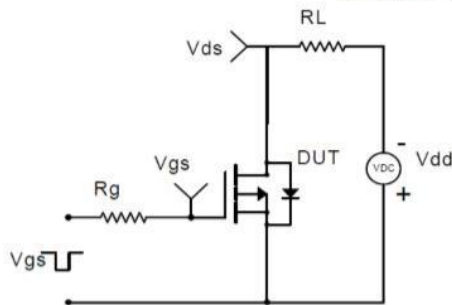


## Test Circuit

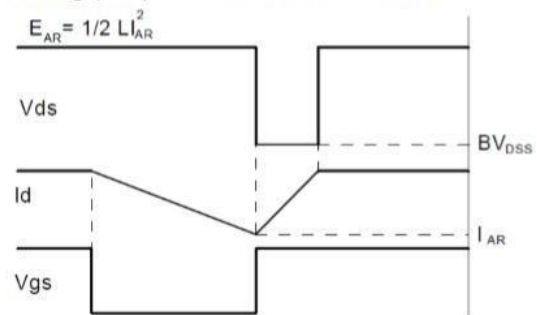
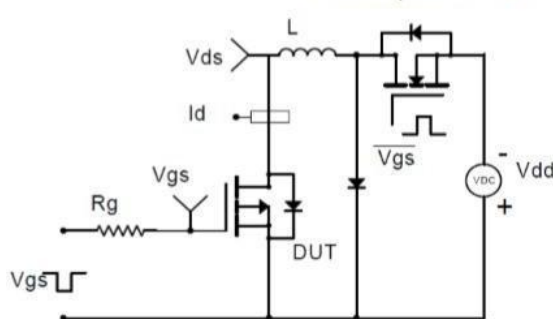
Gate Charge Test Circuit & Waveform



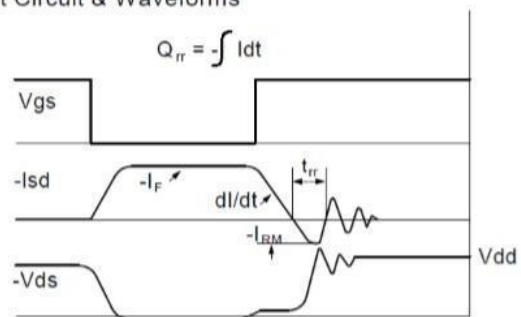
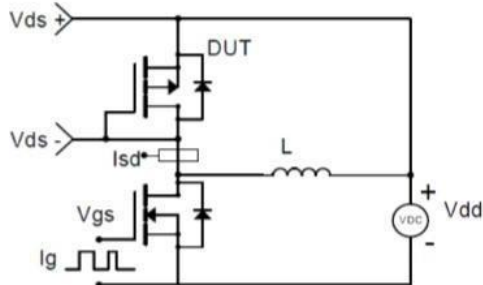
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

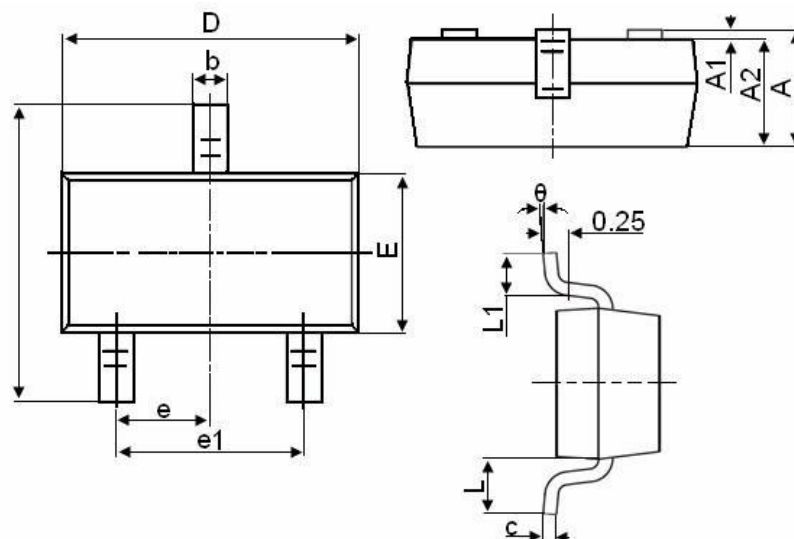


Diode Recovery Test Circuit & Waveforms





## SOT-23-3L Package Information



| Symbol | Dimensions in Millimeters |       |
|--------|---------------------------|-------|
|        | MIN.                      | MAX.  |
| A      | 1.050                     | 1.250 |
| A1     | 0.000                     | 0.100 |
| A2     | 1.050                     | 1.150 |
| b      | 0.300                     | 0.500 |
| c      | 0.100                     | 0.200 |
| D      | 2.800                     | 3.000 |
| E      | 1.500                     | 1.700 |
| E1     | 2.650                     | 2.950 |
| e      | 0.950TYP                  |       |
| e1     | 1.800                     | 2.000 |
| L      | 0.550REF                  |       |
| L1     | 0.300                     | 0.600 |
| θ      | 0°                        | 8°    |



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